

SOT740-3

LBGA256; plastic, low profile ball grid array; 256 bumps; 1.0 mm pitch; 17 mm x 17 mm x 1.7 mm body

15 December 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LBGA256
Package type industry code	LBGA256
Package style descriptive code	LBGA (low profile ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-1-2016
Manufacturer package code	98ASA00346D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	17	-	mm
E	package width		-	-	17	-	mm
A	seated height		-	-	1.7	-	mm
e	nominal pitch		-	-	1	-	mm
n ₂	actual quantity of termination		-	-	256	-	



2. Package outline

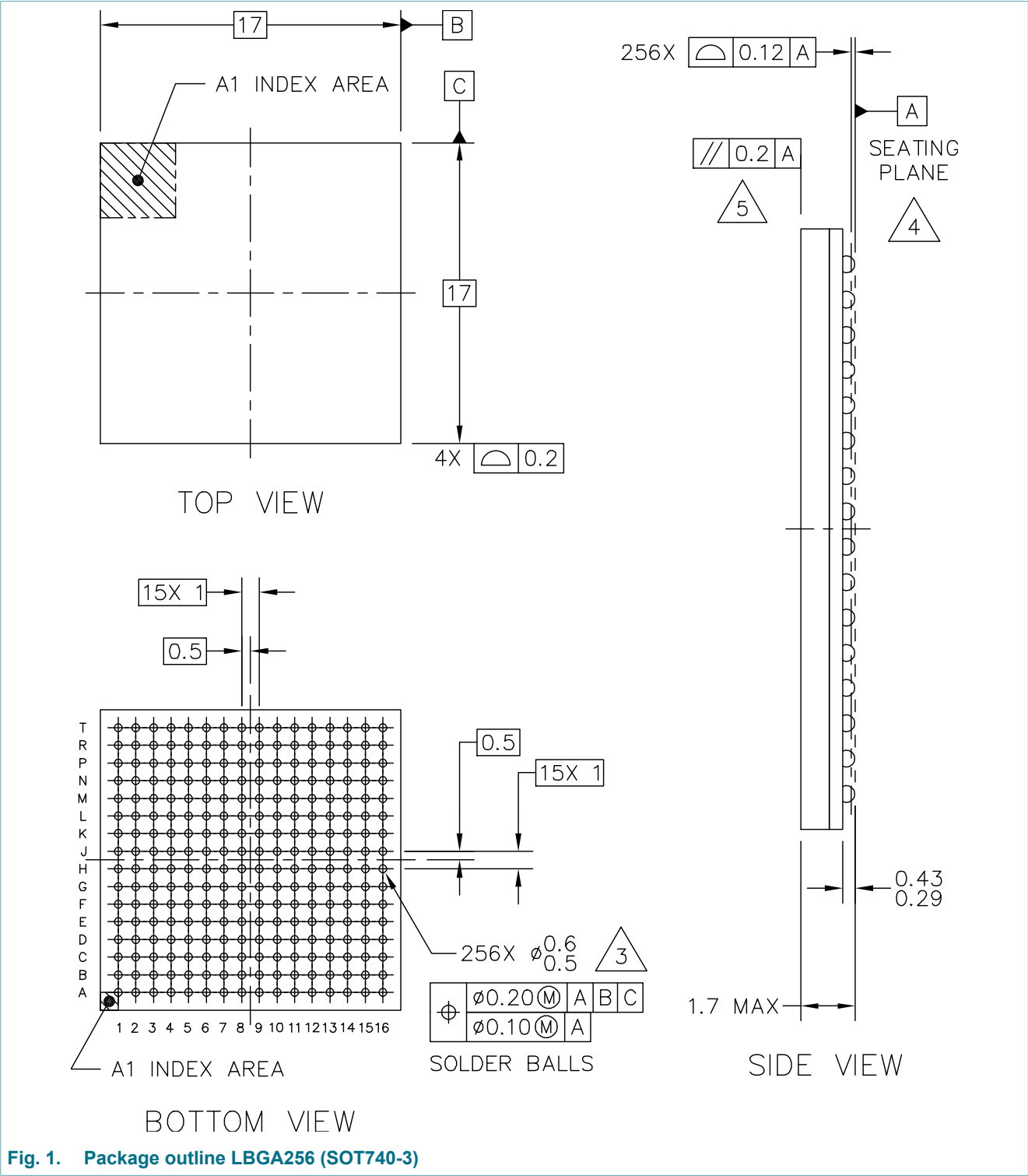


Fig. 1. Package outline LBGA256 (SOT740-3)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

Fig. 2. Package outline note LBGA256 (SOT740-3)

3. Legal information

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